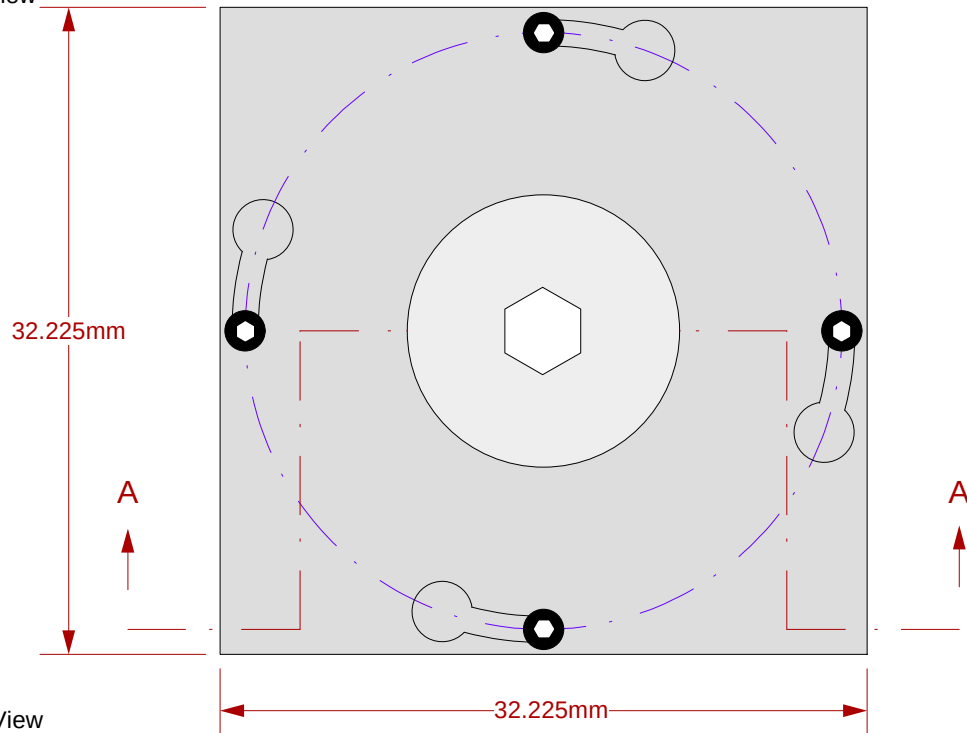
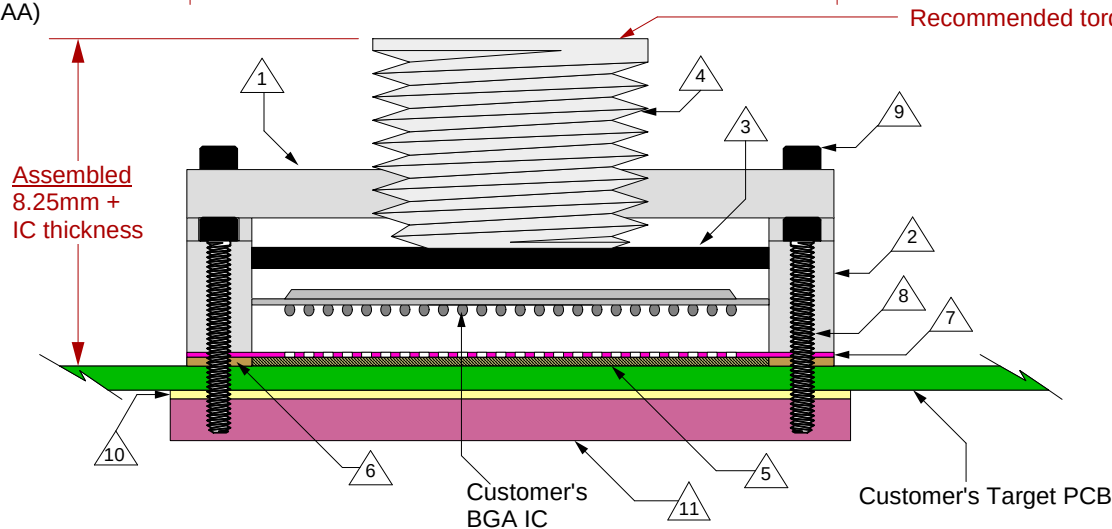


Top View



Side View
(Section AA)



GHz BGA Socket - Direct mount, solderless

Features

- Directly mounts to target PCB (needs tooling holes) with hardware.
- High speed, reliable Elastomer connection
- Minimum real estate required
- Compression plate distributes forces evenly
- Ball guide prevents over compression of elastomer
- Easily removable swivel socket lid

- 1 Socket Lid: Black anodized Aluminum.
Thickness = 2.5mm.
- 2 Socket base: Black anodized Aluminum.
Thickness = 5mm.
- 3 Compression Plate: Black anodized Aluminum.
Thickness = 2.5mm.
- 4 Compression screw: Black anodized Aluminum.
Thickness = 5mm, Hex socket = 5mm.
- 5 Elastomer: 40 micron dia gold plated brass
filaments arranged symmetrically in a silicone
rubber (63.5 degree angle).
Thickness = 0.75mm.
- 6 Elastomer Guide: Non-clad FR4.
Thickness = 0.725mm.
- 7 Ball Guide: Kapton polyimide.
- 8 Socket base screw: Fillister head, Alloy steel with
black oxide finish, 0-80 fine thread, 0.625" long.
- 9 Socket lid screw: Shoulder screw, 18-8 SS, 0-80 fine
thread.
- 10 Insulation Plate: FR4/G10, 1.59mm thick.
- 11 Backing Plate: Anodized Aluminum 6.35mm thick.

SG-BGA-6140 Drawing

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PO BOX 21151 ST. PAUL, MN 55121
Tele: (651) 452-8100
www.ironwoodelectronics.com

Status: Released

Scale: -

Rev: B

Drawing: B.ROUX

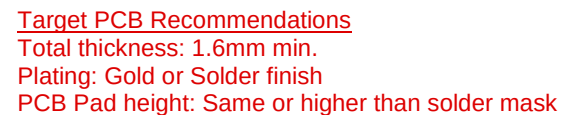
Date: 12/16/04

File: SG-BGA-6140 Dwg

Modified: 5/19/09

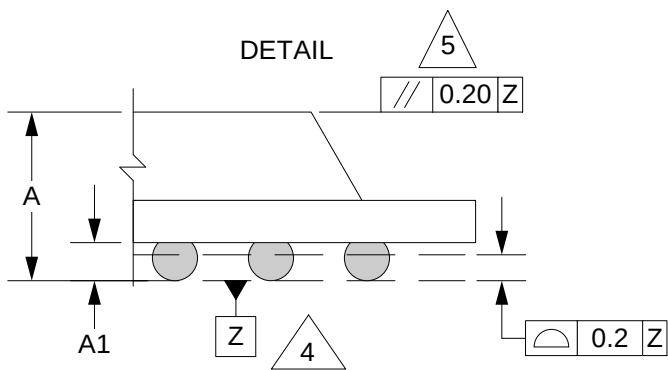
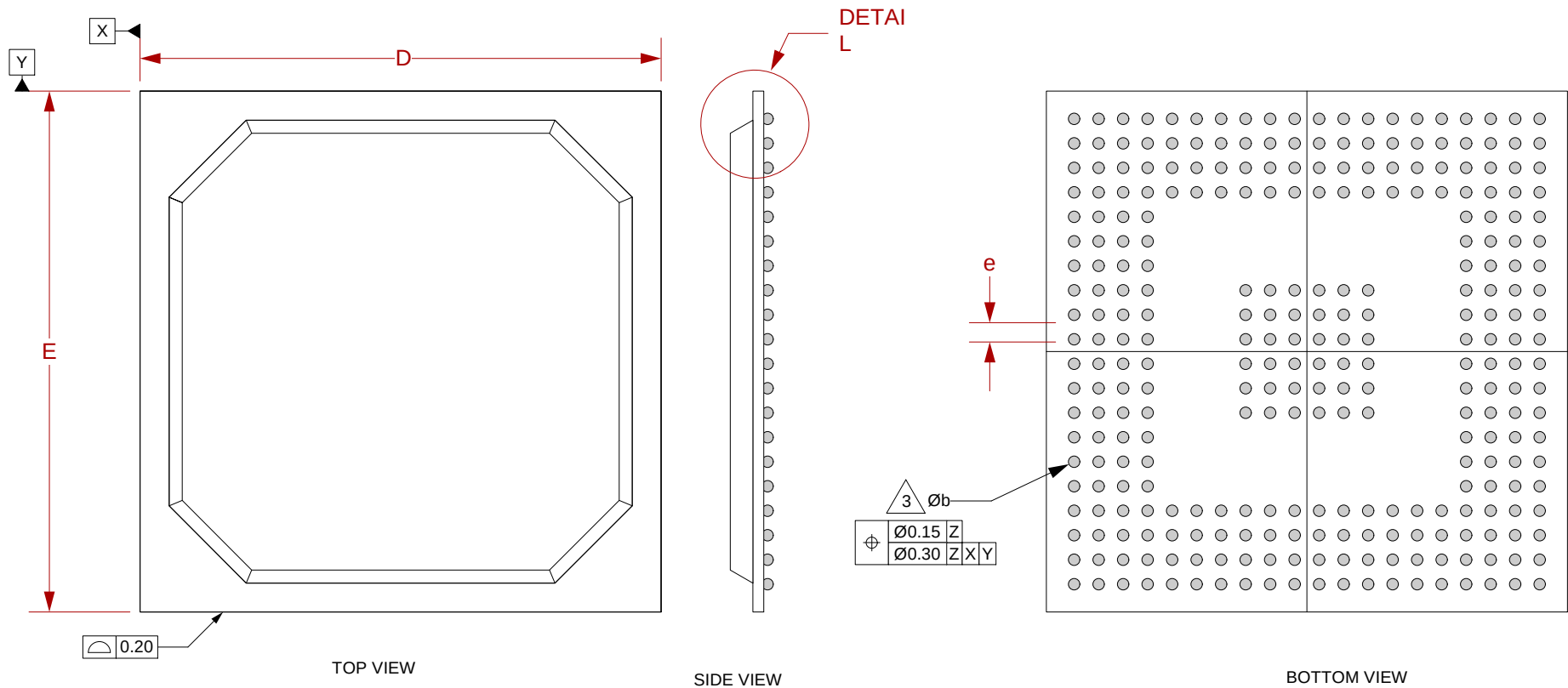
All tolerances: $\pm 0.125\text{mm}$ (unless stated otherwise). Materials and specifications are subject to change without notice.

PAGE 1 of 4



Recommended PCB Layout Tolerances: $\pm 0.025\text{mm}$ [$\pm 0.001"$] unless stated otherwise.

PAGE 2 of 4

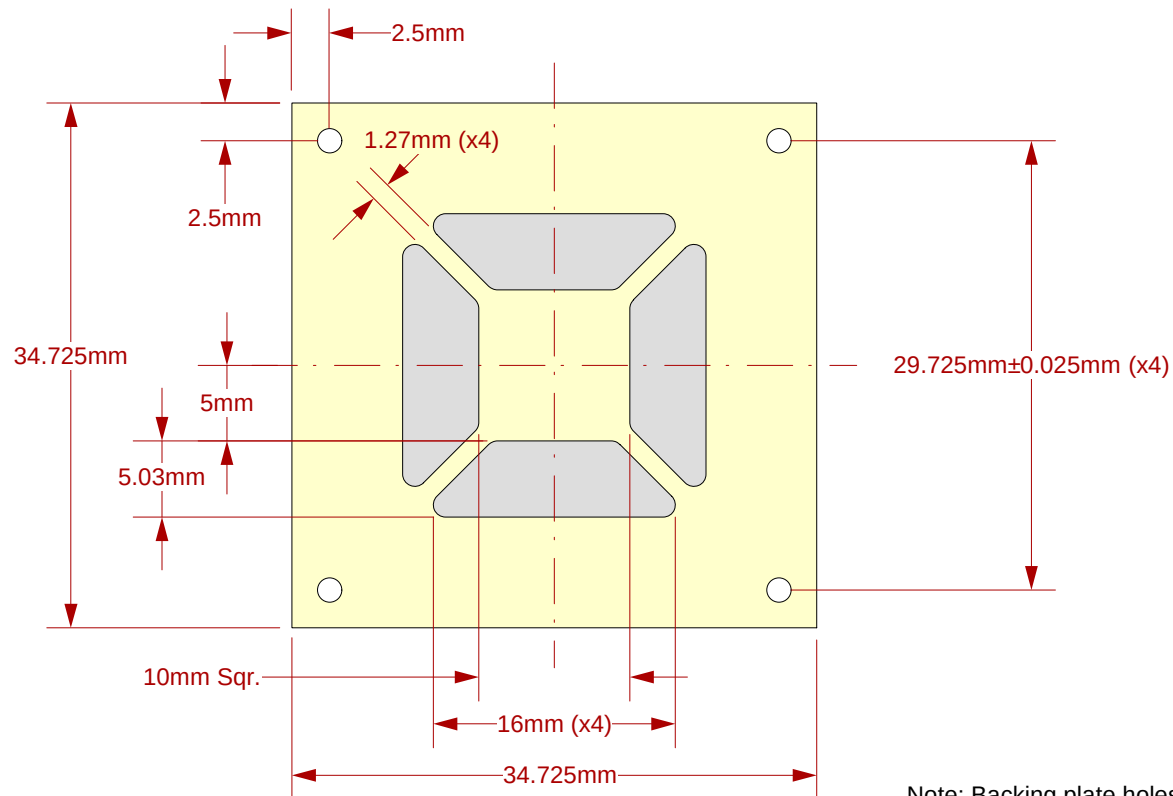


1. Dimensions are in millimeters.
 2. Interpret dimensions and tolerances per ASME Y14.5M-1994.
3. Dimension b is measured at the maximum solder ball diameter, parallel to datum plane Z .
4. Datum Z (seating plane) is defined by the spherical crowns of the solder balls.
5. Parallelism measurement shall exclude any effect of mark on top surface of package.

DIM	MIN	MAX
A		2.21
A1	0.3	0.5
b		0.60
D	27.00 BSC	
E	27.00 BSC	
e	1.27 BSC	

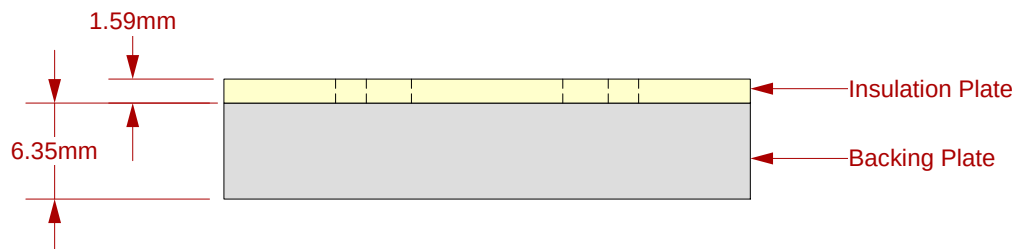
Array 20x20

Top View



Note: Backing plate holes are tapped to accept 0-80 screws.

Side View



Description: Backing Plate with Insulation Plate

All dimensions are in mm.
All tolerances are ± 0.125 mm.
(Unless stated otherwise)

SG-BGA-6140 Drawing

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